

IN THE CLAIMS:

Listing of claims:

1. (currently amended)      A method for forming a head suspension assembly, comprising:  
forming a first layer comprising a sacrificial layer in or on a portion of a substrate;  
forming a ~~film across~~ a second layer comprising a resin on the substrate;  
forming a third layer comprising a photoresist layer on the second layer and patterning a  
the photoresist layer on top of the second layer; film;  
transferring ~~the an~~ image of the patterned photoresist layer through the second layer; film;  
removing the patterned photoresist layer; ~~and~~  
removing the sacrificial layer to form a cavity extending a distance into the substrate; and  
positioning a slider on the second layer after the removing the sacrificial layer.
2. (currently amended)      A method as in claim 1, wherein the second layer film includes silicon.
3. (currently amended)      A method as in claim 1, wherein the transferring the image of the patterned photoresist layer through the second layer film is done using reactive ion etching.
4. (original)      A method as in claim 1, wherein the substrate comprises silicon and the sacrificial layer is formed by etching a trench in the substrate and filling the trench with a metal.
5. (currently amended)      A method as in claim 4, wherein removing the sacrificial layer comprises etching the metal from the trench after the removing the patterned photoresist layer.
6. (canceled)

7. (currently amended) A method as in claim 1, wherein the substrate comprises silicon and the ~~resin film~~ comprises polysilsesquioxone.

8. (previously presented) A method as in claim 1, wherein the cavity extends a width that is no greater than that of the substrate and the cavity extends a depth that is less than a depth of the substrate.

9. (currently amended) A method as in claim 1, further comprising forming a fourth layer comprising an adhesion layer between the substrate and the second layer, film,

10. (currently amended) A method as in claim ~~3~~, 1, wherein, prior to the patterning the photoresist layer, the film is at least one of cured, cross-linked, or oxidized, comprises a resin, and positioning a slider on the resin after the removing the sacrificial layer.

11-20 (canceled)

21. (new) A method for forming a head suspension assembly, comprising:  
forming a sacrificial layer in or on a portion of a substrate;  
forming a polysilsesquioxone layer on the substrate and on at least part of the sacrificial layer;  
forming a photoresist layer on the polysilsesquioxone layer;  
patterning the photoresist layer;  
etching the polysilsesquioxone layer using the patterned photoresist layer as a mask;  
removing the patterned photoresist layer to expose remaining polysilsesquioxone layer;  
removing the sacrificial layer to form a cavity extending a distance into the substrate; and  
positioning a slider on the remaining polysilsesquioxone layer.

22. (new) The method of claim 21, further comprising curing the polysilsesquioxone layer.

23. (new) The method of claim 22, wherein the curing is carried out prior to the positioning a slider on the remaining polysilsesquioxone layer.

24. (new) The method of claim 22, wherein the curing is controlled so that cross-linking of the polysilsesquioxone layer occurs.

25. (new) The method of claim 21, further comprising cross-linking the polysilsesquioxone layer.

26. (new) The method of claim 21, further comprising oxidizing the polysilsesquioxone layer.

27. (new) The method of claim 21, further comprising positioning the slider to be on a part of the remaining polysilsesquioxone layer that is positioned over the cavity.

28. (new) A method for forming a head suspension assembly, comprising:  
forming a sacrificial layer extending a distance into a substrate;  
forming a resin layer on the substrate and on at least part of the sacrificial layer;  
forming a photoresist layer on the resin layer;  
patterning the photoresist layer;  
etching the resin layer using the patterned photoresist layer as a mask;  
removing the patterned photoresist layer to expose remaining resin layer;  
removing the sacrificial layer to form a cavity between at least part of the remaining resin layer and the substrate; and  
positioning a slider on the remaining resin layer.

29. (new) The method of claim 28, further comprising heating the resin layer prior to the forming a photoresist layer on the resin layer.

30. (new) The method of claim 28, wherein resin layer comprises

polysilsesquioxone.

31. (new)      The method of claim 28, further comprising cross-linking at least part of the resin layer prior to the forming the photoresist layer on the resin layer.